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providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas including at least one terminal part therein, at least one of said terminal-forming areas including a plurality of terminal parts directly thereon such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and
pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.

REMARKS

Claims 1, 2, 4, 6 and 7 currently remain in the application. Claims 3, 5, 8 and 9 have been withdrawn as non-elected claims. Claim 1 is amended herein.

Claims 1, 2, 4, 6 and 7 were rejected under 35 U.S.C. 102 as being anticipated by Matsui. In view of the Examiner's reason for the rejection, independent claim 1 is herein amended to say that the plurality of terminal parts previously described merely as being within one of the terminal-forming areas are directly on the terminal-forming area. This excludes the situation where these plurality of terminal parts are stacked one on top of another. This amendment is clearly supported by the specification and hence believed to be enterable. The two "terminal parts (2, 51)", pointed out by the Examiner, are one on top of the other and hence not both of them are directly on what may be referred to as a terminal-forming area. As should be clear from the disclosure in the specification, the gist of the invention is in designing a circuit board such that areas for surface-mounting various parts are effectively distributed. Thus, components stacked one on top of the other as the parts

shown at 2 and 51 in Matsui are not separately surface-mounted and hence are out of regard to the present invention.

With independent claim 1 thus amended, it is believed that the application is now believed to be in condition for allowance.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Four times amended) A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas including at least one terminal part therein, at least one of said terminal-forming areas including a plurality of terminal parts directly thereon such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and
pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.